

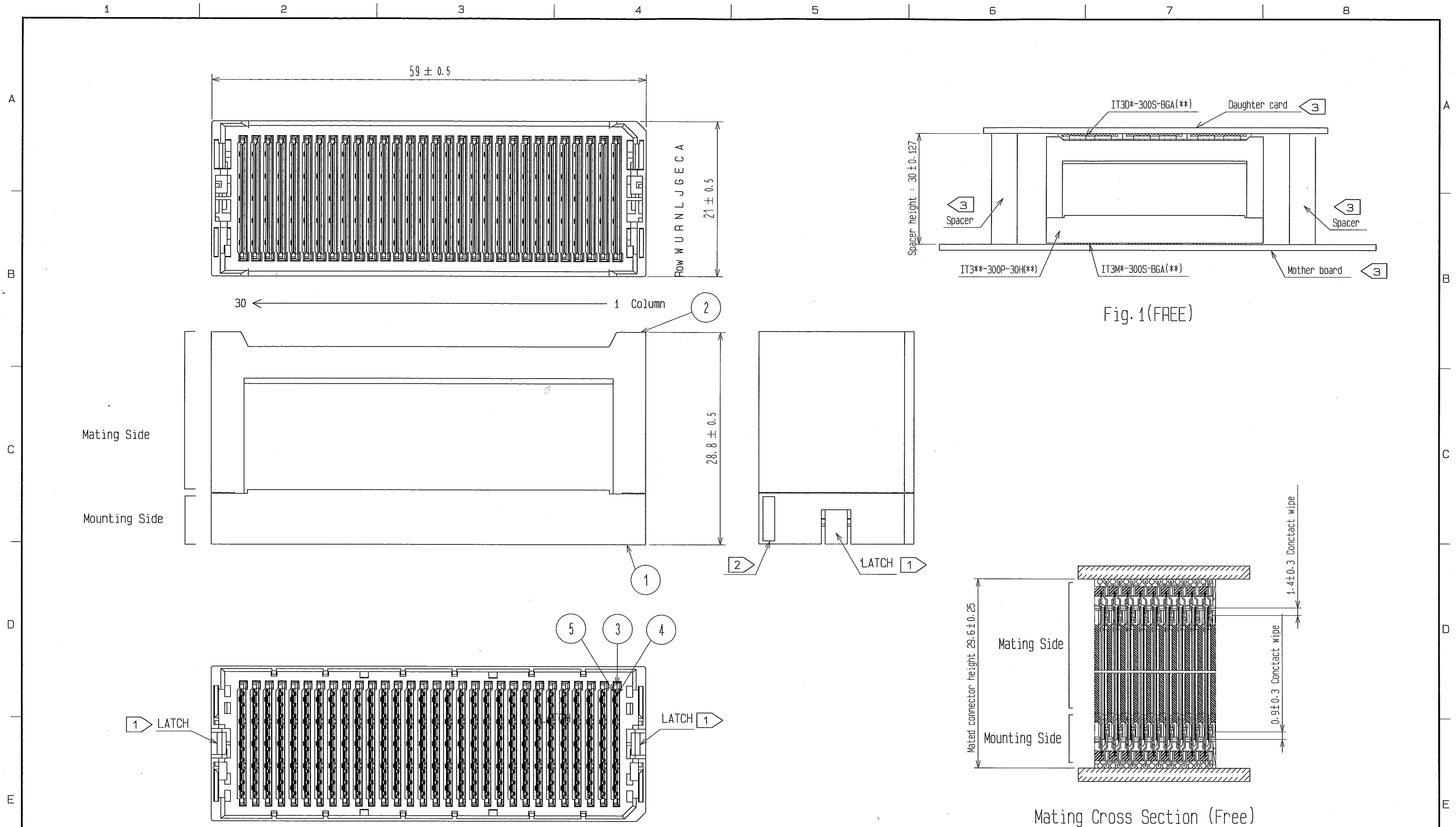
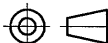


Fig.1(FREE)

Mating Cross Section (Free)

- NOTE.
- ① Mounting side is mated with the receptacle:IT3M-300S-BGA(**) and fixed with the latch.
 - ② Lot No. shall be marked on the indicated position.
 - ③ The indicated mother board and daughter card shall be fastened to the additional reinforcements to prevent the stress on IT3*-300S-BGA(**) solder joints.
 - 4. More information of this product is available in HIROSE document :ETAD-F0347 "IT3 design guideline".
 - 5. This product consists of 300 signal lines and 270 ground lines.
 - 6. 30pcs of this products are packed in a soft tray.

3	LCP	BLACK	UL94V-0					
2	LCP	GRAY	UL94V-0	5	Copper Alloy	CONTACT AREA:NICKEL(1.5μm)+GOLD (0.76μm)		
1	PBT	BLACK	UL94V-0	4	Copper Alloy	CONTACT AREA:NICKEL(1.5μm)+GOLD (0.76μm)		
NO.	MATERIAL	FINISH. REMARKS		NO.	MATERIAL	FINISH. REMARKS		
UNITS mm		SCALE 2 : 1		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
		APPROVED : T. MATSUO		06/20/2008	DRAWING NO. EDC-155706-01			
		CHECKED : T. MATSUO		06/20/2008	PART NO. IT3-300P-30H(03)			
		DESIGNED : M. NAGATA		06/20/2008	CODE NO. CL636-0185-7-03			
		DRAWN : M. NAGATA		06/20/2008	 1/1			